IPC ASSOCIATION ELECTRONIC	Material Con © Copyright 200 international and	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				aterials and	ials and Mfg Information			
upplier	r Information														
Company name* Company unique ID				que ID	ID Unique ID A			ID Authority R			Respo	Response Date*			
nsemi											2023-0	2023-06-08			
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	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Date	Version	M	Manufacturing Site		Weight*	UOM	Unit Type	
		LC87F0G08AUJA-AH 8-bit Microcontroll		ller		2023-06-08 PHM			100.0	mg	Each				
lanufa	cturing Process Information Process Information Plating / Grid Array		Ferminal Base A	Alloy	J-STD-020 MS	I Pating	Peak Proc	ess Rody 7	Cemperatur	May Time at I	eak Tempe	rature Numb	er of Reflow Cy	cles	
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mments			oc moy		•		200		10	100	300	onas s			
m more	information regarding mate	rial composition	nlesse refer to	maga 2											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	2.46	mg	Supplier	Silicon (Si)	7440-21-3		2.4447	mg
			Supplier	Polyimide	Proprietary Data		0.0153	mg
Die Attach	0.59	mg	Supplier	Silver (Ag)	7440-22-4		0.4189	mg
			Supplier	Epoxy resins	129915-35-1		0.1711	mg
Lead Frame	48.0	mg	Supplier	Zinc (Zn)	7440-66-6		0.0912	mg
			Supplier	Iron (Fe)	7439-89-6		1.2432	mg
			Supplier	Copper (Cu)	7440-50-8		46.5984	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0672	mg
Mold Compound-Black	47.28	mg		Epoxy Phenol Resin	proprietary data		5.6736	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1891	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		39.9989	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		1.4184	mg
Plating	1.1	mg	В	Bismuth (Bi)	7440-69-9		0.0066	mg
			Supplier	Tin (Sn)	7440-31-5		1.0934	mg
Wire Bond - Au	0.57	mg	Supplier	Gold (Au)	7440-57-5		0.57	mg